

Stacked Package

Amkor PoP (Package on Package) Dual Sided Test Contactor:

Amkor Technology is now offering the PoP (Package on Package) Dual Sided Test Contactor

Package Stackable Very Thin Fine Pitch BGA (PSvFBGA):

After 3 years of development in package stacking technology and infrastructure, Amkor launched the multiple award winning PSvFBGA (base PoP) platform during the 4th quarter of 2004. The next two years saw many new milestones, from publication of JEDEC mechanical and electrical standards to a range of new customers and applications adopting PoP. By the end of 2006 PSvFBGA became the fastest growing new product in Amkor's history, reflecting the broad industry benefits of PoP and Amkor's leadership position. The next few years promise to provide many new challenges and applications for PoP, as handheld multimedia applications continue to demand higher processing power and memory storage capacities. Amkor is committed to maintain strong development and production capabilities to ensure we are forefront in meeting next generation PoP requirements.

Amkor has expanded our comprehensive PoP family and aligned the roadmap across the supply chain to ensure that PoP will continue to scale with the industry's miniaturization, higher density and performance enhancement requirements.

In 2006 Amkor's PoP family ramped products with 2 die stacked in the PSvFBGA platform. Stacking multiple die in the bottom package allows customers to increase performance and provide further system miniaturization by combining analog + digital or logic + memory devices.

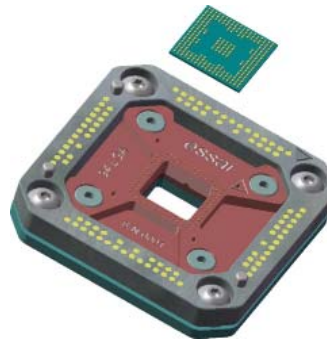
Applications:

PoP packages are designed for products requiring efficient memory architectures including multiple buses and increased memory density & performance, while reducing mounted area. Portable electronic products such as mobile phones (baseband or applications processor + combo memory), digital cameras (image processor + memory), PDAs, portable players (audio / graphics processor + memory), gaming and other mobile applications can benefit from the combination of stacked package and small footprint offered by Amkor's industry leading PoP family.

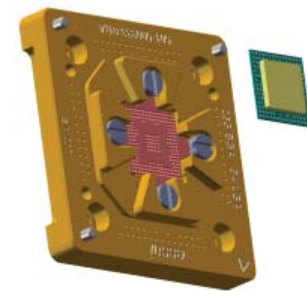
PoP Dual Sided Test Contactor

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| Features: | <ul style="list-style-type: none"> • 0.5 mm pitch Bottom • 0.65 mm pitch Top • Low inductance • Low resistance • Fully qualified for HVM use |
| Benefits: | <ul style="list-style-type: none"> • Single socketing for testing both sides of package • Improved test coverage |

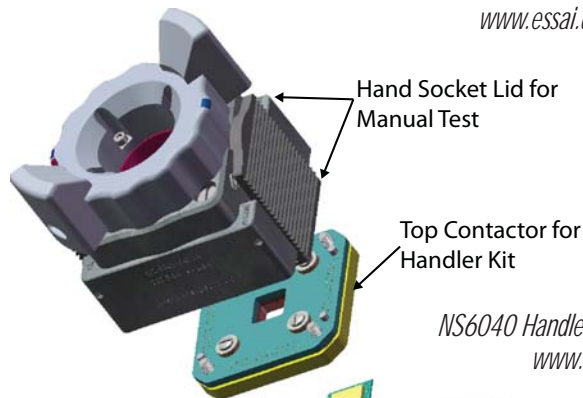
Top Contactor



Bottom Contactor

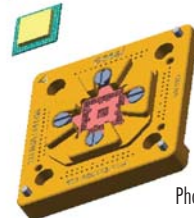


Contactor and Hand Socket Lid developed by Essai
www.essai.com/essai



NS6040 Handler Kit developed by Antares
www.antares-att.com

Handler Kit



Photos courtesy of Essai

Amkor has fully qualified test contactor and handler kit capabilities today!

VISIT AMKOR TECHNOLOGY ONLINE FOR LOCATIONS AND TO VIEW THE MOST CURRENT PRODUCT INFORMATION.

www.amkor.com



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